

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Withdrawn) A method of manufacturing a semiconductor device comprising:
a first step of interposing an adhesive between a surface of a substrate on which an interconnect pattern is formed and a surface of a semiconductor chip on which electrodes are formed, said adhesive having conductive particles dispersed therein; and
a second step in which pressure is applied between said semiconductor chip and said substrate, said interconnect pattern and said electrodes are electrically connected via at least part of said conductive particles of said adhesive, and said adhesive is caused to cover all area of lateral surfaces of said semiconductor chip that is substantially perpendicular to the surface of the semiconductor chip on which the electrodes are formed.
2. (Withdrawn) The method of manufacturing a semiconductor device as defined in claim 1,
wherein said adhesive is provided in the first step at a thickness greater than the interval between said semiconductor chip and said substrate after the second step.
3. (Canceled)
4. (Canceled)
5. (Withdrawn) The method of manufacturing a semiconductor device as defined in claim 1,
wherein before the first step, said adhesive is previously disposed on the surface of said semiconductor chip on which said electrodes are formed.
6. (Withdrawn) The method of manufacturing a semiconductor device as defined in claim 1, wherein before the first step, said adhesive is previously disposed on the surface of said substrate on which said interconnect pattern is formed.

7. (Withdrawn) The method of manufacturing a semiconductor device as defined in claim 1, wherein said adhesive includes a shading material.

8. (Currently Amended) A semiconductor device, comprising:
a semiconductor chip having electrodes;
_____ a substrate having an interconnect pattern; and
_____ an adhesive, said adhesive having a first portion and a second portion, said first portion interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, said second portion overlapping with said semiconductor chip; and ~~said adhesive having~~
~~conductive particles dispersed therein;~~

_____ conductive particles dispersed in said adhesive;
wherein said electrodes and said interconnect pattern are electrically connected via at least part of said conductive particles ~~of said adhesive;~~ and

wherein ~~said adhesive is interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, and~~ said second portion of said adhesive covers all area of lateral surfaces of said semiconductor chip that is substantially perpendicular to the surface of the semiconductor chip on which the electrodes are formed, and a thickness of any part of said second portion of said adhesive is thicker than an interval between the surface of the semiconductor chip on which said electrodes are formed and said interconnect pattern on said substrate.

9. (Canceled)

10. (Canceled)

11. (Previously Presented) The semiconductor device as defined in claim 8, wherein said adhesive is provided to cover said interconnect pattern in its entirety.

12. (Previously Presented) The semiconductor device as defined in claim 8, wherein said adhesive includes a shading material.

13. (Canceled)

14. (Currently Amended) A circuit board on which is mounted a semiconductor device, the semiconductor device comprising:

a semiconductor chip having electrodes;

_____ a substrate having an interconnect pattern; ~~and~~

_____ an adhesive, said adhesive having a first portion and a second portion, said first portion interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, said second portion not overlapping with said semiconductor chip; and ~~said adhesive having conductive particles dispersed therein;~~

_____ conductive particles dispersed in said adhesive;

wherein said electrodes and said interconnect pattern are electrically connected via at least part of said conductive particles ~~of said adhesive;~~ and

wherein ~~said adhesive is interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, and~~ said second portion of said adhesive covers all area of lateral surfaces of said semiconductor chip that is substantially perpendicular to the surface of the semiconductor chip on which the electrodes are formed, and a thickness of any part of said second portion of said adhesive is thicker than an interval between the surface of the semiconductor chip on which said electrodes are formed and said interconnect pattern on said substrate.

15. (Currently Amended) An electronic instrument having a semiconductor device, the semiconductor device comprising:

a semiconductor chip having electrodes;
_____ a substrate having an interconnect pattern; ~~and~~
_____ an adhesive, said adhesive having a first portion and a second portion, said first portion interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, said second portion not overlapping with said semiconductor chip; and ~~said adhesive having~~ conductive particles dispersed therein;
_____ conductive particles dispersed in said adhesive;

wherein said electrodes and said interconnect pattern are electrically connected via at least part of said conductive particles ~~of said adhesive;~~ and

wherein ~~said adhesive is interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, and~~ said second portion of said adhesive covers all area of lateral surfaces of said semiconductor chip that is substantially perpendicular to the surface of the semiconductor chip on which the electrodes are formed, and a thickness of any part of said second portion of said adhesive is thicker than an interval between the surface of the semiconductor chip on which said electrodes are formed and said interconnect pattern on said substrate.

16. (Previously Presented) The semiconductor device as defined in claim 8, wherein at least a part of said adhesive has a thickness substantially the same as said semiconductor chip.

17. (Canceled)

18. (Canceled)

19. (Canceled)

20. (Canceled)

21. (Previously Presented) The circuit board as defined in claim 14,
wherein a part of said adhesive covering all area of lateral surfaces of said semiconductor chip has a thickness substantially the same as said semiconductor chip.
22. (Previously Presented) The electronic instrument as defined in claim 15,
wherein a part of said adhesive covering all area of lateral surfaces of said semiconductor chip has a thickness substantially the same as said semiconductor chip.
23. (Withdrawn) The method of manufacturing a semiconductor device as defined in claim 1,
wherein a part of said adhesive covering all area of said lateral surfaces of said semiconductor chip is formed to have part of said conductive particles dispersed therein.
24. (Currently Amended) The semiconductor device as defined in claim 8,
wherein ~~a part of said adhesive covering all area of said lateral surfaces of said semiconductor chip~~ said second portion of said adhesive has part of said conductive particles dispersed therein.
25. (Currently Amended) The circuit board as defined in claim 14,
wherein ~~a part of said adhesive covering all area of said lateral surfaces of said semiconductor chip~~ said second portion of said adhesive has part of said conductive particles dispersed therein.
26. (Currently Amended) The electronic instrument as defined in claim 15,
wherein ~~a part of said adhesive covering all area of said lateral surfaces of said semiconductor chip~~ said second portion of said adhesive has part of said conductive particles dispersed therein.